

C1206H332F1GACTU

Aliases (C1206H332F1GAC7800) SMD Indust COG HT200C, Ceramic, 3,300 pF, 1%, 100 VDC, COG, SMD, MLCC, High Temperature, Ultra-Stable, Low Loss, 1206, 1.5 mm



Click here for the 3D model.

Chip Size 1206 L 3.2mm +/-0.2mm W 1.6mm +/-0.2mm T 1.1mm +/-0.10mm S 1.5mm MIN B 0.5mm +/-0.25mm	Dimensions	
W 1.6mm +/-0.2mm T 1.1mm +/-0.10mm S 1.5mm MIN	Chip Size	1206
T 1.1mm +/-0.10mm S 1.5mm MIN	L	3.2mm +/-0.2mm
S 1.5mm MIN	W	1.6mm +/-0.2mm
	т	1.1mm +/-0.10mm
B 0.5mm +/-0.25mm	S	1.5mm MIN
,	В	0.5mm +/-0.25mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2500

General Information	
Series	SMD Indust COG HT200C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Low Loss
Features	High Temp, Ultra-Stable, Low Loss
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	25 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	3,300 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	1%
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+200°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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